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(71) **Applicant** (for all designated States except AE, AG, AU, BB, BH, BN, BW, BZ, CA, CY, EG, GB, GD, GH, GM, IE, IL, IN, KE, KN, LC, LK, LS, MT, MW, MY, NA, NG, NZ, OM, PG, QA, RW, SA, SC, SD, SG, SL, SZ, TT, TZ, UG, US, VC, ZA, ZM, ZW): **UNILEVER N.V.** [NL/NL]; Weena 455, 3013 AL Rotterdam (NL).

(71) **Applicant** (for AE, AG, AU, BB, BH, BN, BW, BZ, CA, CY, EG, GB, GD, GH, GM, IE, IL, IN, KE, KN, LC, LK, LS, MT, MW, MY, NA, NG, NZ, OM, PG, QA, RW, SA, SC, SD, SG, SL, SZ, TT, TZ, UG, VC, ZA, ZM, ZW only): **UNILEVER PLC** [GB/GB]; a company registered in England and Wales under company no. 41424 of Unilever House, 100 Victoria Embankment, London Greater London EC4Y 0DY (GB).

(71) **Applicant** (for US only): **CONOPCO, INC., D/B/A UNILEVER** [US/US]; 800 Sylvan Avenue AG West, S. Wing, Englewood Cliffs, New Jersey 07632 (US).

(72) **Inventors**: **DAS, Somnath**; Hindustan Unilever Ltd, Research Centre 64, Main Road, Whitefield, Bangalore 560 066 (IN). **MURALIDHARAN, Girish**; HINDUSTAN UNILEVER Ltd, Research Centre 64, Main Road, Whitefield, Bangalore 560 066 (IN). **PRAMANIK, Amitava**; Hindustan Unilever Ltd, Research Centre 64, Main Road, Whitefield, Bangalore 560 066 (IN).

(74) **Agent**: **WARNER, Guy, Jonathan**; Unilever Patent Group, Olivier van Noortlaan 120, 3133 AT Vlaardingen (NL).

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(54) **Title**: A PROCESS FOR SURFACE MODIFICATION OF MATERIALS

(57) **Abstract**: The present invention relates to surface modification of materials. In particular the invention relates to a process for surface modification of polymeric materials to make the surface non-stick in order to reduce the ability of materials to stick on it and thus provide an easy flow. The process comprises embossing the surface of an object with a pattern comprising micropillars having different shapes (circle, square, rectangular, polygonal prismatic) with an equivalent circular diameter, height and pitch in the range 10-200 microns; applying a layer of adhesive to get a coverage of 0.1 to 5 mg/cm on the embossed surface either by spray coating or dip coating; depositing 0.2 to 1.2 mg/cm of hydrophobic particles wherein the hydrophobic particles have a particle size in the range 0.1 to 10 microns.



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